

CONDUCTIVE MATERIAL COMPOSITIONS, APPARATUS, SYSTEMS, AND METHODS

Abstract of the Disclosure

Various apparatus and systems, as well as methods and articles, may include the use of several compositions, such as solder formulations, including about 78%-83% by weight of lead, about 9%-11% by weight of antimony, about 1%-3% by weight of silver, and a balance of tin. Some embodiments include a process of removing a previously-existing lead finish, and applying a new finish to the lead to improve solder operation compatibility, as well as solder joint reliability in high temperature environments.